Wafer level parallel plate plasma cleaning technology.

PSX307A Plasma Cleaner

Building upon the PSX307 Plasma Cleaner, the PSX307A Plasma Cleaner features an enlarged plasma chamber capacity that improves productivity. In addition, the PSX307A system is able to handle full wafers (both bare and on dicing frames). Besides the increased capacity, Panasonic's original Plasma Monitoring System suppresses abnormal discharges resulting in a secure and efficient production process. Additionally, the option to include a traceability functionality ensures high level process Quality.

Key Features

- Panasonic original Plasma Monitoring System to suppress abnormal discharges
- Traceability functionality
- Flexibility for various types of production
- Achieves high quality products by plasma cleaning and pre-forming from wafer process to assembly process

Panasonic CONNECT

PSX307A Plasma Cleaner

https://ap.connect.panasonic.com/ph/en/psx307a-plasma-cleaner

Model Number	NM-EFP3A
Cleaning Method	Parallel plate RF back-sputtering method
Gas for electrical discharge	Ar [Option:O2, O2 + He]
Substrate dimensions	L 50mm × W 200mm to L 350mm × W 350mm
Substrate thickness (mm)	0.1mm to 2.0mm
Power Source	1-phase AC 200 / 208 / 220 / 230 / 240 ± 10V, 50 / 60Hz , 6.00kVA
Adhesive dispenser	0.49MPa、25 L/min [A.N.R]
Dimensions (mm)	W 900mm × D 1150mm × H 1650mm
Mass (Weight)	(Excluding touch panel, operating part, and signal tower / 630kg)